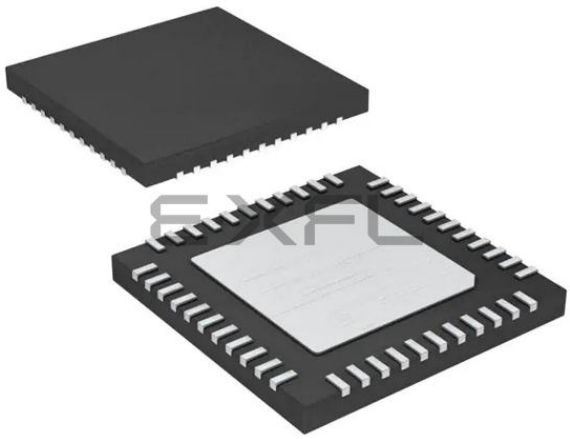

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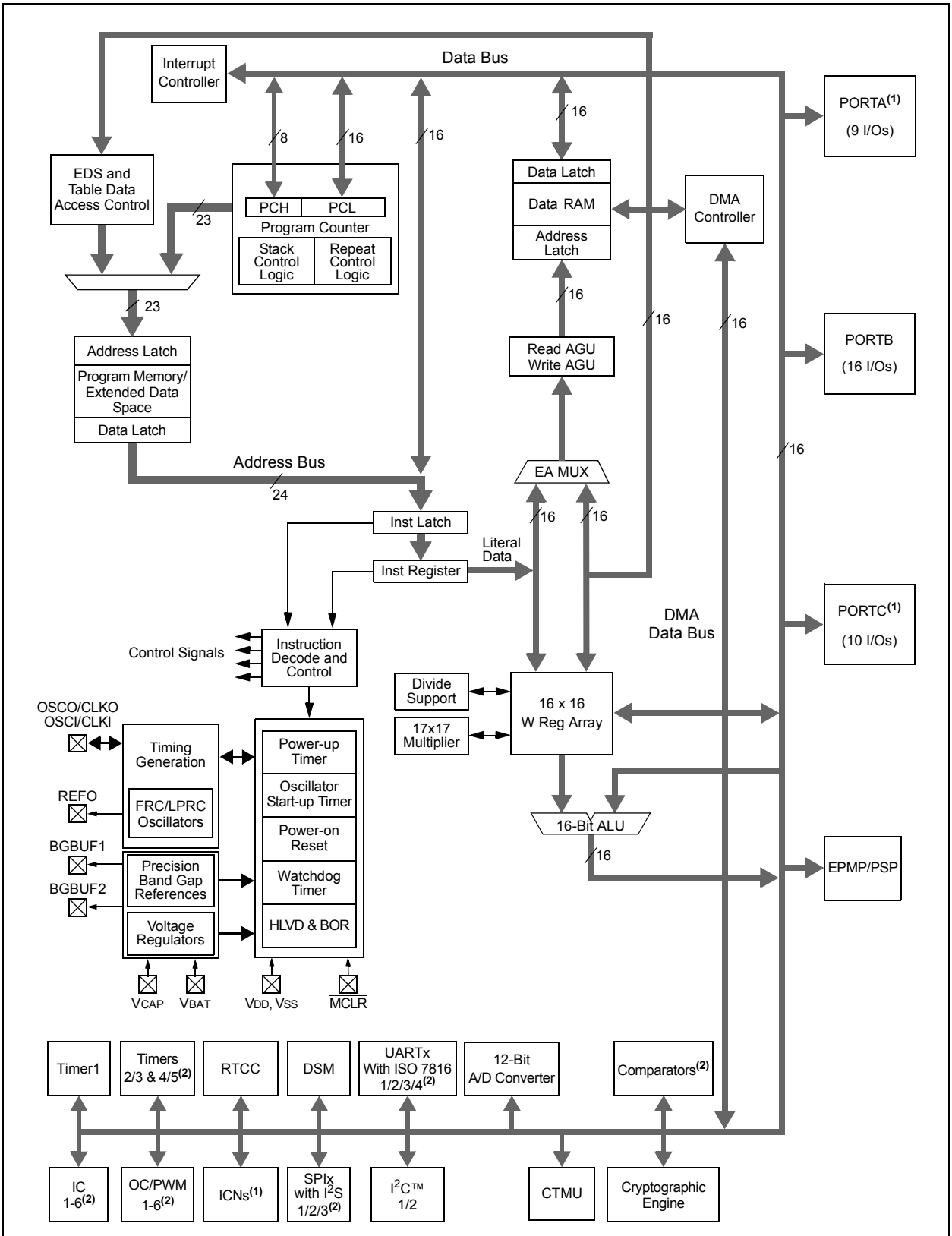
Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	32MHz
Connectivity	I²C, IrDA, LINbus, PMP/PSP, SmartCard, SPI, UART/USART
Peripherals	AES, Brown-out Detect/Reset, DMA, I²S, HLVD, POR, PWM, WDT
Number of I/O	35
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 3.6V
Data Converters	A/D 13x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24fj64ga204-i-ml

FIGURE 1-1: PIC24FJ128GA204 FAMILY GENERAL BLOCK DIAGRAM



Note 1: Not all I/O pins or features are implemented on all device pinout configurations. See Table 1-3 for specific implementations by pin count.
2: These peripheral I/Os are only accessible through remappable pins.

TABLE 1-3: PIC24FJ128GA204 FAMILY PINOUT DESCRIPTIONS (CONTINUED)

Pin Function	Pin Number/Grid Locator			I/O	Input Buffer	Description
	28-Pin SPDIP/SOIC/ SSOP	28-Pin QFN-S	44-Pin TQFP/QFN			
CTED1	2	27	19	I	ANA	CTMU External Edge Inputs.
CTED2	3	28	20	I	ANA	
CTED3	16	13	43	I	ANA	
CTED4	18	15	1	I	ANA	
CTED5	25	22	14	I	ANA	
CTED6	26	23	15	I	ANA	
CTED7	—	—	5	I	ANA	
CTED8	7	4	24	I	ANA	
CTED9	22	19	9	I	ANA	
CTED10	17	14	44	I	ANA	
CTED11	21	18	8	I	ANA	
CTED12	5	2	22	I	ANA	
CTED13	6	3	23	I	ANA	
CTPLS	24	21	11	O	—	CTMU Pulse Output.
CV_{REF}	25	22	14	O	ANA	Comparator Voltage Reference Output.
CV_{REF+}	2	27	19	I	ANA	Comparator Reference Voltage (high) Input.
CV_{REF-}	3	28	20	I	ANA	Comparator Reference Voltage (low) Input.
INT0	16	13	43	I	ST	External Interrupt Input 0.
HLVDIN	23	20	10	I	ANA	High/Low-Voltage Detect Input.
$\overline{MCLR}$	1	26	18	I	ST	Master Clear (device Reset) Input. This line is brought low to cause a Reset.
OSCI	9	6	30	I	ANA	Main Oscillator Input Connection.
OSCO	10	7	31	O	—	Main Oscillator Output Connection.
PGC1	5	2	22	I/O	ST	In-Circuit Debugger/Emulator/ICSP™ Programming Clock.
PGC2	22	19	9	I/O	ST	
PGC3	15	12	42	I/O	ST	
PGD1	4	1	21	I/O	ST	
PGD2	21	18	8	I/O	ST	
PGD3	14	11	41	I/O	ST	

Legend: ST = Schmitt Trigger input
ANA = Analog input
I^2C = ST with I^2C™ or SMBus levels
TTL = TTL compatible input
O = Output
I = Input
P = Power

TABLE 1-3: PIC24FJ128GA204 FAMILY PINOUT DESCRIPTIONS (CONTINUED)

Pin Function	Pin Number/Grid Locator			I/O	Input Buffer	Description
	28-Pin SPDIP/SOIC/ SSOP	28-Pin QFN-S	44-Pin TQFP/QFN			
RP0	4	1	21	I/O	ST	Remappable Peripherals (input or output).
RP1	5	2	22	I/O	ST	
RP2	6	3	23	I/O	ST	
RP3	7	4	24	I/O	ST	
RP5	14	11	41	I/O	ST	
RP6	3,15	12	42	I/O	ST	
RP7	16	13	43	I/O	ST	
RP8	17	14	44	I/O	ST	
RP9	18	15	1	I/O	ST	
RP10	21	18	8	I/O	ST	
RP11	22	19	9	I/O	ST	
RP12	23	20	10	I/O	ST	
RP13	24	21	11	I/O	ST	
RP14	25	22	14	I/O	ST	
RP15	26	23	15	I/O	ST	
RP16	—	—	25	I/O	ST	
RP17	—	—	26	I/O	ST	
RP18	—	—	27	I/O	ST	
RP19	—	—	36	I/O	ST	
RP20	—	—	37	I/O	ST	
RP21	—	—	38	I/O	ST	
RP22	—	—	2	I/O	ST	
RP23	—	—	3	I/O	ST	
RP24	—	—	4	I/O	ST	
RP25	—	—	5	I/O	ST	
RPI4	11	8	33	I	ST	Remappable Peripheral (input).
RTCC	25	22	14	O	—	Real-Time Clock Alarm/Seconds Pulse Output.
SCL1	17	14	44	I/O	I^2C	I2C1 Synchronous Serial Clock Input/Output.
SCL2	7	4	24	I/O	I^2C	I2C2 Synchronous Serial Clock Input/Output.
SCLKI	12	9	34	I	—	Secondary Oscillator Digital Clock Input.
SDA1	18	15	1	I/O	I^2C	I2C1 Data Input/Output.
SDA2	6	3	23	I/O	I^2C	I2C2 Data Input/Output.
SOSCI	11	8	33	I	ANA	Secondary Oscillator/Timer1 Clock Input.
SOSCO	12	9	34	O	ANA	Secondary Oscillator/Timer1 Clock Output.

Legend: ST = Schmitt Trigger input TTL = TTL compatible input I = Input
ANA = Analog input O = Output P = Power
I^2C = ST with I^2C™ or SMBus levels

TABLE 4-21: DMA REGISTER MAP

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
DMACON	0450	DMAEN	—	—	—	—	—	—	—	—	—	—	—	—	—	—	PRSSEL	0000
DMABUF	0452	DMA Transfer Data Buffer																0000
DMAL	0454	DMA High Address Limit Register																0000
DMAH	0456	DMA Low Address Limit Register																0000
DMACH0	0458	—	—	—	r	—	NULLW	RELOAD	CHREQ	SAMODE1	SAMODE0	DAMODE1	DAMODE0	TRMODE1	TRMODE0	SIZE	CHEN	0000
DMAINT0	045A	DBUFWF	—	CHSEL5	CHSEL4	CHSEL3	CHSEL2	CHSEL1	CHSEL0	HIGHIF	LOWIF	DONEIF	HALFIF	OVRUNIF	—	—	HALFEN	0000
DMASRC0	045C	DMA Channel 0 Source Address Register																0000
DMADST0	045E	DMA Channel 0 Destination Address Register																0000
DMACNT0	0460	DMA Channel 0 Transaction Count Register																0001
DMACH1	0462	—	—	—	r	—	NULLW	RELOAD	CHREQ	SAMODE1	SAMODE0	DAMODE1	DAMODE0	TRMODE1	TRMODE0	SIZE	CHEN	0000
DMAINT1	0464	DBUFWF	—	CHSEL5	CHSEL4	CHSEL3	CHSEL2	CHSEL1	CHSEL0	HIGHIF	LOWIF	DONEIF	HALFIF	OVRUNIF	—	—	HALFEN	0000
DMASRC1	0466	DMA Channel 1 Source Address Register																0000
DMADST1	0468	DMA Channel 1 Destination Address Register																0000
DMACNT1	046A	DMA Channel 1 Transaction Count Register																0001
DMACH2	046C	—	—	—	r	—	NULLW	RELOAD	CHREQ	SAMODE1	SAMODE0	DAMODE1	DAMODE0	TRMODE1	TRMODE0	SIZE	CHEN	0000
DMAINT2	046E	DBUFWF	—	CHSEL5	CHSEL4	CHSEL3	CHSEL2	CHSEL1	CHSEL0	HIGHIF	LOWIF	DONEIF	HALFIF	OVRUNIF	—	—	HALFEN	0000
DMASRC2	0470	DMA Channel 2 Source Address Register																0000
DMADST2	0472	DMA Channel 2 Destination Address Register																0000
DMACNT2	0474	DMA Channel 2 Transaction Count Register																0001
DMACH3	0476	—	—	—	r	—	NULLW	RELOAD	CHREQ	SAMODE1	SAMODE0	DAMODE1	DAMODE0	TRMODE1	TRMODE0	SIZE	CHEN	0000
DMAINT3	0478	DBUFWF	—	CHSEL5	CHSEL4	CHSEL3	CHSEL2	CHSEL1	CHSEL0	HIGHIF	LOWIF	DONEIF	HALFIF	OVRUNIF	—	—	HALFEN	0000
DMASRC3	047A	DMA Channel 3 Source Address Register																0000
DMADST3	047C	DMA Channel 3 Destination Address Register																0000
DMACNT3	047E	DMA Channel 3 Transaction Count Register																0001
DMACH4	0480	—	—	—	r	—	NULLW	RELOAD	CHREQ	SAMODE1	SAMODE0	DAMODE1	DAMODE0	TRMODE1	TRMODE0	SIZE	CHEN	0000
DMAINT4	0482	DBUFWF	—	CHSEL5	CHSEL4	CHSEL3	CHSEL2	CHSEL1	CHSEL0	HIGHIF	LOWIF	DONEIF	HALFIF	OVRUNIF	—	—	HALFEN	0000
DMASRC4	0484	DMA Channel 4 Source Address Register																0000
DMADST4	0486	DMA Channel 4 Destination Address Register																0000
DMACNT4	0488	DMA Channel 4 Transaction Count Register																0001
DMACH5	048A	—	—	—	r	—	NULLW	RELOAD	CHREQ	SAMODE1	SAMODE0	DAMODE1	DAMODE0	TRMODE1	TRMODE0	SIZE	CHEN	0000
DMAINT5	048C	DBUFWF	—	CHSEL5	CHSEL4	CHSEL3	CHSEL2	CHSEL1	CHSEL0	HIGHIF	LOWIF	DONEIF	HALFIF	OVRUNIF	—	—	HALFEN	0000
DMASRC5	048E	DMA Channel 5 Source Address Register																0000
DMADST5	0490	DMA Channel 5 Destination Address Register																0000
DMACNT5	0492	DMA Channel 5 Transaction Count Register																0001

Legend: — = unimplemented, read as '0'; r = reserved. Reset values are shown in hexadecimal.

4.2.5.1 Data Read from EDS

In order to read the data from the EDS space first, an Address Pointer is set up by loading the required EDS page number into the DSRPAG register and assigning the offset address to one of the W registers. Once the above assignment is done, the EDS window is enabled by setting bit 15 of the Working register assigned with the offset address; then, the contents of the pointed EDS location can be read.

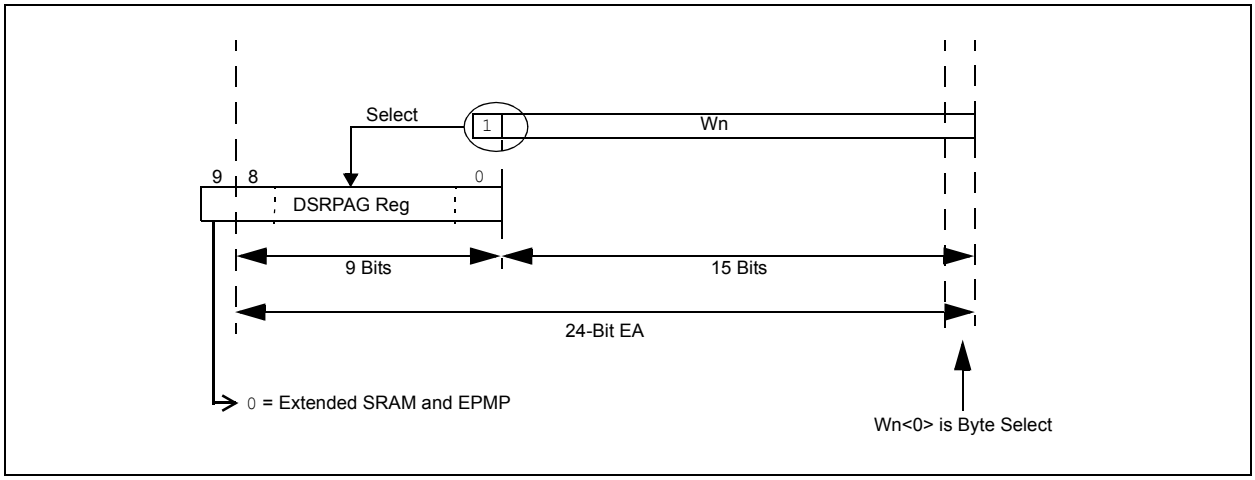
Figure 4-5 illustrates how the EDS space address is generated for read operations.

When the Most Significant bit of the EA is '1' and DSRPAG<9> = 0, the lower 9 bits of DSRPAG are concatenated to the lower 15 bits of the EA to form a 24-bit EDS space address for read operations.

Example 4-1 shows how to read a byte, word and double-word from EDS.

Note:	All read operations from EDS space have an overhead of one instruction cycle. Therefore, a minimum of two instruction cycles are required to complete an EDS read. EDS reads under the `REPEAT` instruction; the first two accesses take three cycles and the subsequent accesses take one cycle.

FIGURE 4-5: EDS ADDRESS GENERATION FOR READ OPERATIONS



EXAMPLE 4-1: EDS READ CODE IN ASSEMBLY

```
; Set the EDS page from where the data to be read
    mov         #0x0002, w0
    mov         w0, DSRPAG      ;page 2 is selected for read
    mov         #0x0800, w1     ;select the location (0x800) to be read
    bset        w1, #15         ;set the MSB of the base address, enable EDS mode

;Read a byte from the selected location
    mov.b       [w1++], w2      ;read Low byte
    mov.b       [w1++], w3      ;read High byte

;Read a word from the selected location
    mov         [w1], w2        ;

;Read Double - word from the selected location
    mov.d       [w1], w2        ;two word read, stored in w2 and w3
```

REGISTER 6-1: NVMCON: FLASH MEMORY CONTROL REGISTER

R/S-0, HC(1)	R/W-0(1)	R-0, HSC(1)	U-0	U-0	U-0	U-0	U-0
WR	WREN	WRERR	—	—	—	—	—
bit 15							bit 8

U-0	R/W-0(1)	U-0	U-0	R/W-0(1)	R/W-0(1)	R/W-0(1)	R/W-0(1)
—	ERASE	—	—	NVMOP3(2)	NVMOP2(2)	NVMOP1(2)	NVMOP0(2)
bit 7							bit 0

Legend:	S = Settable bit	HC = Hardware Clearable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown
HSC = Hardware Settable/Clearable bit			

bit 15 **WR:** Write Control bit(1)
- 1 = Initiates a Flash memory program or erase operation; the operation is self-timed and the bit is cleared by hardware once the operation is complete
- 0 = Program or erase operation is complete and inactive

bit 14 **WREN:** Write Enable bit(1)
- 1 = Enables Flash program/erase operations
- 0 = Inhibits Flash program/erase operations

bit 13 **WRERR:** Write Sequence Error Flag bit(1)
- 1 = An improper program or erase sequence attempt, or termination has occurred (bit is set automatically on any set attempt of the WR bit)
- 0 = The program or erase operation completed normally

bit 12-7 **Unimplemented:** Read as '0'

bit 6 **ERASE:** Erase/Program Enable bit(1)
- 1 = Performs the erase operation specified by the NVMOP<3:0> bits on the next WR command
- 0 = Performs the program operation specified by the NVMOP<3:0> bits on the next WR command

bit 5-4 **Unimplemented:** Read as '0'

bit 3-0 **NVMOP<3:0>:** NVM Operation Select bits(1,2)
- 1111 = Memory bulk erase operation (ERASE = 1) or no operation (ERASE = 0)(3)
- 0011 = Memory word program operation (ERASE = 0) or no operation (ERASE = 1)
- 0010 = Memory page erase operation (ERASE = 1) or no operation (ERASE = 0)
- 0001 = Memory row program operation (ERASE = 0) or no operation (ERASE = 1)

Note 1: These bits can only be reset on a Power-on Reset.

2: All other combinations of NVMOP<3:0> are unimplemented.

3: Available in ICSP™ mode only; refer to the device programming specification.

6.6.1 PROGRAMMING ALGORITHM FOR FLASH PROGRAM MEMORY

The user can program one row of Flash program memory at a time. To do this, it is necessary to erase the 8-row erase block containing the desired row. The general process is:

1. Read eight rows of program memory (512 instructions) and store in data RAM.
2. Update the program data in RAM with the desired new data.
3. Erase the block (see Example 6-1):
   a) Set the NVMOPx bits (NVMCON<3:0>) to '0010' to configure for block erase. Set the ERASE (NVMCON<6>) and WREN (NVMCON<14>) bits.
   b) Write the starting address of the block to be erased into the TBLPAG and W registers.
   c) Write 55h to NVMKEY.
   d) Write AAh to NVMKEY.
   e) Set the WR bit (NVMCON<15>). The erase cycle begins and the CPU stalls for the duration of the erase cycle. When the erase is done, the WR bit is cleared automatically.
4. Write the first 64 instructions from data RAM into the program memory buffers (see Example 6-3).
5. Write the program block to Flash memory:
   a) Set the NVMOPx bits to '0001' to configure for row programming. Clear the ERASE bit and set the WREN bit.
   b) Write 55h to NVMKEY.
   c) Write AAh to NVMKEY.
   d) Set the WR bit. The programming cycle begins and the CPU stalls for the duration of the write cycle. When the write to Flash memory is done, the WR bit is cleared automatically.
6. Repeat Steps 4 and 5, using the next available 64 instructions from the block in data RAM by incrementing the value in TBLPAG, until all 512 instructions are written back to Flash memory.

For protection against accidental operations, the write initiate sequence for NVMKEY must be used to allow any erase or program operation to proceed. After the programming command has been executed, the user must wait for the programming time until programming is complete. The two instructions following the start of the programming sequence should be NOPs, as shown in Example 6-4.

EXAMPLE 6-1: ERASING A PROGRAM MEMORY BLOCK (ASSEMBLY LANGUAGE CODE)

```
; Set up NVMCON for block erase operation
    MOV    #0x4042, W0                    ;
    MOV    W0, NVMCON                     ; Initialize NVMCON
; Init pointer to row to be ERASED
    MOV    #tblpage(PROG_ADDR), W0        ;
    MOV    W0, TBLPAG                     ; Initialize Program Memory (PM) Page Boundary SFR
    MOV    #tbloffset(PROG_ADDR), W0      ; Initialize in-page EA<15:0> pointer
    TBLWTL W0, [W0]                       ; Set base address of erase block
    DISI   #5                             ; Block all interrupts with priority <7
                                          ; for next 5 instructions
    MOV.B  #0x55, W0
    MOV    W0, NVMKEY                     ; Write the 0x55 key
    MOV.B  #0xAA, W1                      ;
    MOV    W1, NVMKEY                     ; Write the 0xAA key
    BSET   NVMCON, #WR                    ; Start the erase sequence
    NOP                                   ; Insert two NOPs after the erase
    NOP                                   ; command is asserted
```

6.6.2 PROGRAMMING A SINGLE WORD OF FLASH PROGRAM MEMORY

If a Flash location has been erased, it can be programmed using Table Write instructions to write an instruction word (24-bit) into the write latch. The TBLPAG register is loaded with the 8 Most Significant Bytes (MSBs) of the Flash address. The TBLWTL and TBLWTH instructions write the desired data into the write latches and specify the lower 16 bits of the program memory address to write to. To configure the NVMCON register for a word write, set the NVMOPx bits (NVMCON<3:0>) to '0011'. The write is performed by executing the unlock sequence and setting the WR bit (see Example 6-5). An equivalent procedure in 'C' compiler language, using the MPLAB® C30 compiler and built-in hardware functions, is shown in Example 6-6.

EXAMPLE 6-5: PROGRAMMING A SINGLE WORD OF FLASH PROGRAM MEMORY

```
; Setup a pointer to data Program Memory
    MOV     #tblpage(PROG_ADDR), W0       ;
    MOV     W0, TBLPAG                    ;Initialize PM Page Boundary SFR
    MOV     #tbloffset(PROG_ADDR), W0     ;Initialize a register with program memory address

    MOV     #LOW_WORD_N, W2               ;
    MOV     #HIGH_BYTE_N, W3              ;
    TBLWTL  W2, [W0]                      ; Write PM low word into program latch
    TBLWTH  W3, [W0++]                    ; Write PM high byte into program latch

; Setup NVMCON for programming one word to data Program Memory
    MOV     #0x4003, W0                   ;
    MOV     W0, NVMCON                    ; Set NVMOP bits to 0011

    DISI    #5                            ; Disable interrupts while the KEY sequence is written
    MOV.B   #0x55, W0                     ; Write the key sequence
    MOV     W0, NVMKEY
    MOV.B   #0xAA, W0
    MOV     W0, NVMKEY
    BSET    NVMCON, #WR                   ; Start the write cycle
    NOP                                   ; Required delays
    NOP
```

EXAMPLE 6-6: PROGRAMMING A SINGLE WORD OF FLASH PROGRAM MEMORY ('C' LANGUAGE CODE)

```
// C example using MPLAB C30
unsigned int offset;
unsigned long progAddr = 0xXXXXXX;            // Address of word to program
unsigned int progDataL = 0xXXXX;              // Data to program lower word
unsigned char progDataH = 0xXX;               // Data to program upper byte

//Set up NVMCON for word programming
NVMCON = 0x4003;                              // Initialize NVMCON

//Set up pointer to the first memory location to be written
TBLPAG = progAddr>>16;                        // Initialize PM Page Boundary SFR
offset = progAddr & 0xFFFF;                   // Initialize lower word of address

//Perform TBLWT instructions to write latches
__builtin_tblwtl(offset, progDataL);          // Write to address low word
__builtin_tblwth(offset, progDataH);          // Write to upper byte
asm("DISI #5");                               // Block interrupts with priority <7
                                              // for next 5 instructions
__builtin_write_NVM();                        // C30 function to perform unlock
                                              // sequence and set WR
```

REGISTER 8-22: IPC1: INTERRUPT PRIORITY CONTROL REGISTER 1

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	T2IP2	T2IP1	T2IP0	—	OC2IP2	OC2IP1	OC2IP0
bit 15							bit 8

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	IC2IP2	IC2IP1	IC2IP0	—	DMA0IP2	DMA0IP1	DMA0IP0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14-12 **T2IP<2:0>:** Timer2 Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 11 **Unimplemented:** Read as '0'

bit 10-8 **OC2IP<2:0>:** Output Compare Channel 2 Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 7 **Unimplemented:** Read as '0'

bit 6-4 **IC2IP<2:0>:** Input Capture Channel 2 Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 3 **Unimplemented:** Read as '0'

bit 2-0 **DMA0IP<2:0>:** DMA Channel 0 Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

REGISTER 8-24: IPC3: INTERRUPT PRIORITY CONTROL REGISTER 3

U-0	U-0	U-0	U-0	U-0	R/W-1	R/W-0	R/W-0
—	—	—	—	—	DMA1IP2	DMA1IP1	DMA1IP0
bit 15							bit 8

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	AD1IP2	AD1IP1	AD1IP0	—	U1TXIP2	U1TXIP1	U1TXIP0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-11 **Unimplemented:** Read as '0'

bit 10-8 **DMA1IP<2:0>:** DMA Channel 1 Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 7 **Unimplemented:** Read as '0'

bit 6-4 **AD1IP<2:0>:** A/D Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 3 **Unimplemented:** Read as '0'

bit 2-0 **U1TXIP<2:0>:** UART1 Transmitter Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

REGISTER 8-42: IPC22: INTERRUPT PRIORITY CONTROL REGISTER 22

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	SPI3TXIP2	SPI3TXIP1	SPI3TXIP0	—	SPI3IP2	SPI3IP1	SPI3IP0
bit 15							bit 8

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	U4TXIP2	U4TXIP1	U4TXIP0	—	U4RXIP2	U4RXIP1	U4RXIP0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14-12 **SPI3TXIP<2:0>:** SPI3 Transmit Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 11 **Unimplemented:** Read as '0'

bit 10-8 **SPI3IP<2:0>:** SPI3 General Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 7 **Unimplemented:** Read as '0'

bit 6-4 **U4TXIP<2:0>:** UART4 Transmitter Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 3 **Unimplemented:** Read as '0'

bit 2-0 **U4RXIP<2:0>:** UART4 Receiver Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

10.4.2 EXITING DEEP SLEEP MODE

Deep Sleep mode exits on any one of the following events:

- POR event on VDD supply. If there is no DSBOR circuit to rearm the VDD supply POR circuit, the external VDD supply must be lowered to the natural arming voltage of the POR circuit.
- DSWDT time-out. When the DSWDT times out, the device exits Deep Sleep.
- RTCC alarm (if RTCEN = 1).
- Assertion ('0') of the $\overline{\text{MCLR}}$ pin.
- Assertion of the INT0 pin (if the interrupt was enabled before Deep Sleep mode was entered). The polarity configuration is used to determine the assertion level ('0' or '1') of the pin that will cause an exit from Deep Sleep mode. Exiting from Deep Sleep mode requires a change on the INT0 pin while in Deep Sleep mode.

Note:	Any interrupt pending when entering Deep Sleep mode is cleared.

Exiting Deep Sleep generally does not retain the state of the device and is equivalent to a Power-on Reset (POR) of the device. Exceptions to this include the RTCC (if present), which remains operational through the wake-up, the DSGPRx registers and the DSWDT.

Wake-up events that occur from the time Deep Sleep exits until the time the POR sequence completes are not ignored. The DSWAKE register will capture ALL wake-up events, from setting the DSEN bit to clearing the RELEASE bit.

The sequence for exiting Deep Sleep mode is:

1. After a wake-up event, the device exits Deep Sleep and performs a POR. The DSEN bit is cleared automatically. Code execution resumes at the Reset vector.
2. To determine if the device exited Deep Sleep, read the Deep Sleep bit, DPSLP (RCON<10>). This bit will be set if there was an exit from Deep Sleep mode. If the bit is set, clear it.
3. Determine the wake-up source by reading the DSWAKE register.
4. Determine if a DSBOR event occurred during Deep Sleep mode by reading the DSBOR bit (DSCON<1>).
5. If application context data has been saved, read it back from the DSGPR0 and DSGPR1 registers.
6. Clear the RELEASE bit (DSCON<0>).

10.4.3 SAVING CONTEXT DATA WITH THE DSGPRx REGISTERS

As exiting Deep Sleep mode causes a POR, most Special Function Registers reset to their default POR values. In addition, because VCORE power is not supplied in Deep Sleep mode, information in data RAM may be lost when exiting this mode.

Applications which require critical data to be saved prior to Deep Sleep, may use the Deep Sleep General Purpose registers, DSGPR0 and DSGPR1, or data EEPROM (if available). Unlike other SFRs, the contents of these registers are preserved while the device is in Deep Sleep mode. After exiting Deep Sleep, software can restore the data by reading the registers and clearing the RELEASE bit (DSCON<0>).

Note:	User software should enable the DSSWEN (CW4<8>) Configuration Fuse bit for saving critical data in the DSGPRx registers.

10.4.4 I/O PINS IN DEEP SLEEP MODE

During Deep Sleep, the general purpose I/O pins retain their previous states and the Secondary Oscillator (SOSC) will remain running, if enabled. Pins that are configured as inputs (TRISx bit is set), prior to entry into Deep Sleep, remain high-impedance during Deep Sleep. Pins that are configured as outputs (TRISx bit is clear), prior to entry into Deep Sleep, remain as output pins during Deep Sleep. While in this mode, they continue to drive the output level determined by their corresponding LATx bit at the time of entry into Deep Sleep.

Once the device wakes back up, all I/O pins continue to maintain their previous states, even after the device has finished the POR sequence and is executing application code again. Pins configured as inputs during Deep Sleep remain high-impedance and pins configured as outputs continue to drive their previous value. After waking up, the TRISx and LATx registers, and the SOSCEN bit (OSCCON<1>) are reset. If firmware modifies any of these bits or registers, the I/O will not immediately go to the newly configured states. Once the firmware clears the RELEASE bit (DSCON<0>), the I/O pins are "released". This causes the I/O pins to take the states configured by their respective TRISx and LATx bit values.

This means that keeping the SOSC running after waking up requires the SOSCEN bit to be set before clearing RELEASE.

If the Deep Sleep BOR (DSBOR) is enabled, and a DSBOR or a true POR event occurs during Deep Sleep, the I/O pins will be immediately released, similar to clearing the RELEASE bit. All previous state information will be lost, including the general purpose DSGPR0 and DSGPR1 contents.

REGISTER 15-2: OCxCON2: OUTPUT COMPARE x CONTROL REGISTER 2 (CONTINUED)

bit 4-0 **SYNCSEL<4:0>:** Trigger/Synchronization Source Selection bits

11111 = This OC module(1)
11110 = OCTRIG1 external input
11101 = OCTRIG2 external input
11100 = CTMU(2)
11011 = A/D(2)
11010 = Comparator 3(2)
11001 = Comparator 2(2)
11000 = Comparator 1(2)
10111 = Reserved
10110 = Reserved
10101 = Input Capture 6(2)
10100 = Input Capture 5(2)
10011 = Input Capture 4(2)
10010 = Input Capture 3(2)
10001 = Input Capture 2(2)
10000 = Input Capture 1(2)
01111 = Timer5
01110 = Timer4
01101 = Timer3
01100 = Timer2
01011 = Timer1
01010 = Reserved
01001 = Reserved
01000 = Reserved
00111 = Reserved
00110 = Output Compare 6(1)
00101 = Output Compare 5(1)
00100 = Output Compare 4(1)
00011 = Output Compare 3(1)
00010 = Output Compare 2(1)
00001 = Output Compare 1(1)
00000 = Not synchronized to any other module

Note 1: Never use an OCx module as its own trigger source, either by selecting this mode or another equivalent SYNCSELx setting.

2: Use these inputs as trigger sources only and never as sync sources.

3: The DCB<1:0> bits are double-buffered in PWM modes only (OCM<2:0> (OCxCON1<2:0>) = 111, 110).

REGISTER 16-1: SPIxCON1L: SPIx CONTROL REGISTER 1 LOW (CONTINUED)

bit 11-10 **MODE<32,16>:** Serial Word Length bits(1,4)

AUDEN = 0:

MODE32	MODE16	COMMUNICATION
1	x	32-Bit
0	1	16-Bit
0	0	8-Bit

AUDEN = 1:

MODE32	MODE16	COMMUNICATION
1	1	24-Bit Data, 32-Bit FIFO, 32-Bit Channel/64-Bit Frame
1	0	32-Bit Data, 32-Bit FIFO, 32-Bit Channel/64-Bit Frame
0	1	16-Bit Data, 16-Bit FIFO, 32-Bit Channel/64-Bit Frame
0	0	16-Bit Data, 16-Bit FIFO, 16-Bit Channel/32-Bit Frame

bit 9 **SMP:** SPIx Data Input Sample Phase bit

Master Mode:
1 = Input data is sampled at the end of data output time
0 = Input data is sampled at the middle of data output time

Slave Mode:
Input data is always sampled at the middle of data output time, regardless of the SMP bit setting.

bit 8 **CKE:** SPIx Clock Edge Select bit(1)

1 = Transmit happens on transition from active clock state to Idle clock state
0 = Transmit happens on transition from Idle clock state to active clock state

bit 7 **SSEN:** Slave Select Enable bit (Slave mode)(2)

1 = $\overline{SSx}$ pin is used by the macro in Slave mode; $\overline{SSx}$ pin is used as the slave select input
0 = $\overline{SSx}$ pin is not used by the macro ($\overline{SSx}$ pin will be controlled by the port I/O)

bit 6 **CKP:** Clock Polarity Select bit

1 = Idle state for clock is a high level; active state is a low level
0 = Idle state for clock is a low level; active state is a high level

bit 5 **MSTEN:** Master Mode Enable bit

1 = Master mode
0 = Slave mode

bit 4 **DISSDI:** Disable SDIx Input Port bit

1 = SDIx pin is not used by the module; pin is controlled by the port function
0 = SDIx pin is controlled by the module

bit 3 **DISSCK:** Disable SCKx Output Port bit

1 = SCKx pin is not used by the module; pin is controlled by the port function
0 = SCKx pin is controlled by the module

bit 2 **MCLKEN:** Master Clock Enable bit(3)

1 = MCLK is used by the BRG
0 = PBCLK is used by the BRG

bit 1 **SPIFE:** Frame Sync Pulse Edge Select bit

1 = Frame Sync pulse (Idle-to-active edge) coincides with the first bit clock
0 = Frame Sync pulse (Idle-to-active edge) precedes the first bit clock

bit 0 **ENHBUF:** Enhanced Buffer Mode Enable bit

1 = Enhanced Buffer Mode is enabled
0 = Enhanced Buffer Mode is disabled

Note 1: When AUDEN = 1, this module functions as if CKE = 0, regardless of its actual value.
2: When FRMEN = 1, SSEN is not used.
3: MCLKEN can only be written when the SPIEN bit = 0.
4: This channel is not meaningful for DSP/PCM mode as LRC follows FRMSYPW.

REGISTER 17-1: I2CxCONL: I2Cx CONTROL REGISTER LOW

R/W-0	U-0	R/W-0, HC	R/W-1	R/W-0	R/W-0	R/W-0	R/W-0
I2CEN	—	I2CSIDL	SCLREL(1)	STRICT	A10M	DISSLW	SMEN
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0, HC	R/W-0, HC	R/W-0, HC	R/W-0, HC	R/W-0, HC
GCEN	STREN	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN
bit 7							bit 0

Legend:	HC = Hardware Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **I2CEN:** I2Cx Enable bit (writable from SW only)
1 = Enables the I2Cx module, and configures the SDAx and SCLx pins as serial port pins
0 = Disables the I2Cx module; all I²C™ pins are controlled by port functions

bit 14 **Unimplemented:** Read as '0'

bit 13 **I2CSIDL:** I2Cx Stop in Idle Mode bit
1 = Discontinues module operation when device enters Idle mode
0 = Continues module operation in Idle mode

bit 12 **SCLREL:** SCLx Release Control bit (I²C Slave mode only)(1)
Module resets and (I2CEN = 0) sets SCLREL = 1.
If STREN = 0:(2)
1 = Releases clock
0 = Forces clock low (clock stretch)
If STREN = 1:
1 = Releases clock
0 = Holds clock low (clock stretch); user may program this bit to '0'; clock stretch is at the next SCLx low

bit 11 **STRICT:** I2Cx Strict Reserved Address Rule Enable bit
1 = Strict reserved addressing is enforced; for reserved addresses, refer to Table 17-1.
(In Slave Mode) – The device doesn't respond to reserved address space and addresses falling in that category are NACKed.
(In Master Mode) – The device is allowed to generate addresses with reserved address space.
0 = Reserved addressing would be Acknowledged.
(In Slave Mode) – The device will respond to an address falling in the reserved address space. When there is a match with any of the reserved addresses, the device will generate an ACK.
(In Master Mode) – Reserved.

bit 10 **A10M:** 10-Bit Slave Address Flag bit
1 = I2CxADD is a 10-bit slave address
0 = I2CADD is a 7-bit slave address

bit 9 **DISSLW:** Slew Rate Control Disable bit
1 = Slew rate control is disabled for Standard Speed mode (100 kHz, also disabled for 1 MHz mode)
0 = Slew rate control is enabled for High-Speed mode (400 kHz)

bit 8 **SMEN:** SMBus Input Levels Enable bit
1 = Enables input logic so thresholds are compliant with the SMBus specification
0 = Disables SMBus-specific inputs

Note 1: Automatically cleared to '0' at the beginning of slave transmission; automatically cleared to '0' at the end of slave reception.
2: Automatically cleared to '0' at the beginning of slave transmission.

TABLE 32-3: DC CHARACTERISTICS: TEMPERATURE AND VOLTAGE SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 2.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
Operating Voltage							
DC10	VDD	**Supply Voltage**	2.0	—	3.6	V	BOR disabled
			VBOR	—	3.6	V	BOR enabled
DC12	VDR	**RAM Data Retention Voltage**(1)	Greater of: VPORREL or VBOR	—	—	V	VBOR used only if BOR is enabled (BOREN = 1)
DC16	VPOR	**VDD Start Voltage** to Ensure Internal Power-on Reset Signal	VSS	—	—	V	**(Note 2)**
DC16A	VPORREL	**VDD Power-on Reset Release Voltage**	1.80	1.88	1.95	V	**(Note 3)**
DC17A	SRVDD	**Recommended VDD Rise Rate** to Ensure Internal Power-on Reset Signal	0.05	—	—	V/ms	0-3.3V in 66 ms, 0-2.5V in 50 ms **(Note 2)**
DC17B	VBOR	**Brown-out Reset Voltage** on VDD Transition, High-to-Low	2.0	2.1	2.2	V	**(Note 3)**

Note 1: This is the limit to which VDD may be lowered and the RAM contents will always be retained.

2: If the VPOR or SRVDD parameters are not met, or the application experiences slow power-down VDD ramp rates, it is recommended to enable and use BOR.

3: On a rising VDD power-up sequence, application firmware execution begins at the higher of the VPORREL or VBOR level (when BOREN = 1).

TABLE 32-5: DC CHARACTERISTICS: IDLE CURRENT (IIDLE)

DC CHARACTERISTICS			Standard Operating Conditions: 2.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Parameter No.	**Typical(1)**	**Max**	**Units**	**Operating Temperature**	**VDD**	**Conditions**
Idle Current (IIDLE)(2)						
DC40	116	150	μA	-40°C to +85°C	2.0V	1 MIPS, FOSC = 2 MHz
	—	170	μA	+125°C	2.0V	
	123	160	μA	-40°C to +85°C	3.3V	
	—	180	μA	+125°C	3.3V	
DC43	0.39	0.5	mA	-40°C to +85°C	2.0V	4 MIPS, FOSC = 8 MHz
	—	0.52	mA	+125°C	2.0V	
	0.41	0.54	mA	-40°C to +85°C	3.3V	
	—	0.56	mA	+125°C	3.3V	
DC47	1.5	1.9	mA	-40°C to +85°C	2.0V	16 MIPS, FOSC = 32 MHz
	—	2	mA	+125°C	2.0V	
	1.6	2.0	mA	-40°C to +85°C	3.3V	
	—	2.1	mA	+125°C	3.3V	
DC50	0.54	0.61	mA	-40°C to +85°C	2.0V	4 MIPS (FRC), FOSC = 8 MHz
	0.54	0.64	mA	-40°C to +85°C	3.3V	
DC51	17	78	μA	-40°C to +85°C	2.0V	LPRC (15.5 KIPS), FOSC = 31 kHz
	—	128	μA	+125°C	2.0V	
	18	80	μA	-40°C to +85°C	3.3V	
	—	130	μA	+125°C	3.3V	

Note 1: Data in the “Typical” column is at 3.3V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: Base IIDLE current is measured with the core off, the clock on and all modules turned off. Peripheral Module Disable SFR registers are zeroed. All I/O pins are configured as inputs and pulled to VSS.

TABLE 32-15: VBAT OPERATING VOLTAGE SPECIFICATIONS

Param No.	Symbol	Characteristic	Min	Typ	Max	Units	Comments
DVB01	VBT	Operating Voltage	1.6	—	3.6	V	Battery connected to the VBAT pin
DVB10	VBTADC	VBAT A/D Monitoring Voltage Specification(1)	1.6	—	3.6	V	A/D monitoring the VBAT pin using the internal A/D channel

Note 1: Measuring the A/D value using the A/D is represented by the equation: Measured Voltage = ((VBAT/2)/VDD) * 4096) for 12-bit A/D

TABLE 32-16: CTMU CURRENT SOURCE SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 2.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended					
Param No.	Sym	Characteristic	Min	Typ(1)	Max(3)	Units	Comments	Conditions
DCT10	IOUT1	CTMU Current Source, Base Range	208	550	797	nA	CTMUICON<9:8> = 00	2.5V < VDD < VDDMAX
DCT11	IOUT2	CTMU Current Source, 10x Range	3.32	5.5	7.67	µA	CTMUICON<9:8> = 01	
DCT12	IOUT3	CTMU Current Source, 100x Range	32.22	55	77.78	µA	CTMUICON<9:8> = 10	
DCT13	IOUT4	CTMU Current Source, 1000x Range	322	550	777	µA	CTMUICON<9:8> = 11(2)	
DCT21	VΔ	Temperature Diode Voltage Change per Degree Celsius	—	-3	—	mV/°C		

Note 1: Nominal value at the center point of the current trim range (CTMUICON<15:10> = 000000).

2: Do not use this current range with a temperature sensing diode.

3: Maximum values are tested at +85°C.

FIGURE 32-6: I²C™ BUS START/STOP BITS TIMING CHARACTERISTICS (SLAVE MODE)

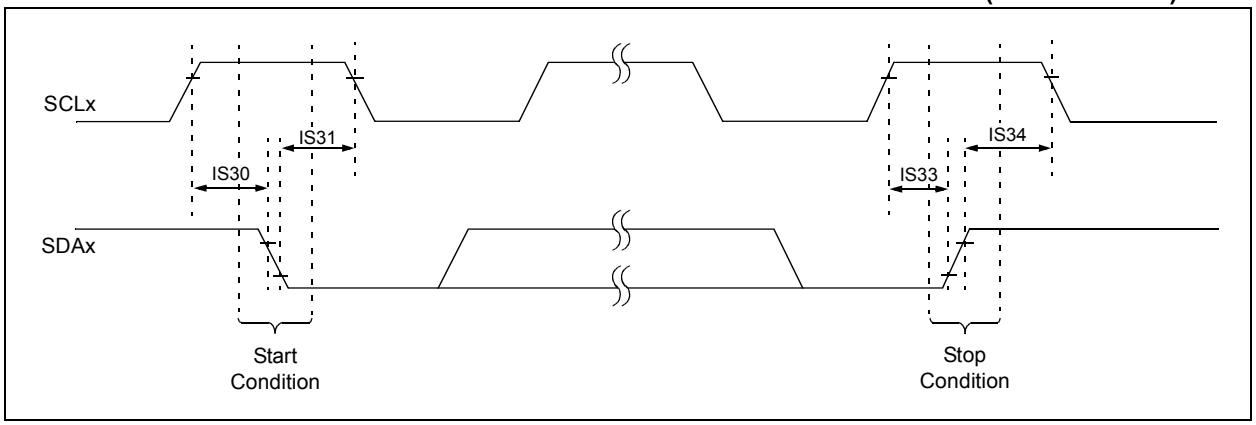


TABLE 32-24: I²C™ BUS START/STOP BIT TIMING REQUIREMENTS (SLAVE MODE)

AC CHARACTERISTICS				Standard Operating Conditions: 2.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Param No.	**Symbol**	**Characteristic**		**Min**	**Max**	**Units**	**Conditions**
IS30	TSU:STA	Start Condition Setup Time	100 kHz mode	4.7	—	µs	Only relevant for Repeated Start condition
			400 kHz mode	0.6	—	µs	
			1 MHz mode(1)	0.25	—	µs	
IS31	THD:STA	Start Condition Hold Time	100 kHz mode	4.0	—	µs	After this period, the first clock pulse is generated
			400 kHz mode	0.6	—	µs	
			1 MHz mode(1)	0.25	—	µs	
IS33	TSU:STO	Stop Condition Setup Time	100 kHz mode	4.7	—	µs	
			400 kHz mode	0.6	—	µs	
			1 MHz mode(1)	0.6	—	µs	
IS34	THD:STO	Stop Condition Hold Time	100 kHz mode	4000	—	ns	
			400 kHz mode	600	—	ns	
			1 MHz mode(1)	250	—	ns	

Note 1: Maximum Pin Capacitance = 10 pF for all I²C pins (for 1 MHz mode only).

NOTES: